# 2.5V / 3.3V Differential 4:1 **Mux Input to 1:2 LVPECL** Clock/Data Fanout / **Translator**

# Multi-Level Inputs w/ Internal Termination

The NB7L572 is a high performance differential 4:1 Clock/Data input multiplexer and a 1:2 LVPECL Clock/Data fanout buffer. The INx/ $\overline{\text{INx}}$  inputs includes internal 50  $\Omega$  termination resistors and will accept differential LVPECL, CML, or LVDS logic levels. The NB7L572 incorporates a pair of Select pins that will choose one of four differential inputs and will produce two identical LVPECL output copies of Clock or Data operating up to 7 GHz or 10 Gb/s, respectively. As such, NB7L572 is ideal for SONET, GigE, Fiber Channel, Backplane and other Clock/Data distribution applications.

The NB7L572 INx/INx inputs, outputs and core logic are powered by a 2.5 V  $\pm 5\%$  V or 3.3 V  $\pm 10\%$  power supply. The two differential LVPECL outputs will swing 750 mV when externally terminated with a 50  $\Omega$  resistor to  $V_{CC}$  – 2 V, and are optimized for low skew and minimal jitter.

The NB7L572 is offered in a low profile 5x5 mm 32-pin QFN Pb-free package. Application notes, documentation are a ail ble at www. nsom .com.

is a member of th performance clock products.

#### **Features**

- Input Data Rate > 10.7 Gb/s Typical
- Data Dependent Jitter < 15 ps
- Maximum Input Clock Frequency > 7 GHz Typical
- Random Clock Jitter < 0.8 ps RMS
- Low Skew 1:2 LVPECL Outputs, < 15 ps max
- 4:1 Multi-Level Mux Inputs, Accepts LVPECL, CML LVDS
- 150 ps Typical Propagation Delay
- 60 ps Typical Rise and Fall Times
- Differential LVPECL Outputs, 750 mV Peak-to-Peak, Typical
- Operating Range:  $V_{CC} = 2.375 \text{ V}$  to 3.6 V
- Internal 50 Ω Input Termination Resistors
- V<sub>REFAC</sub> Reference Output
- -40°C to +85°C Ambient Operating Temperature
- These are Pb-Free Devices

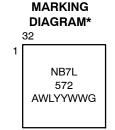


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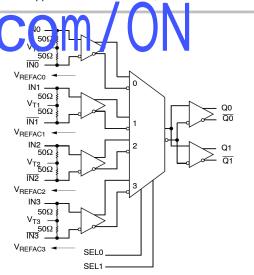
QFN32 **MN SUFFIX** CASE 488AM



= Assembly Site WI = Wafer Lot YY = Year WW = Work Week = Pb-Free Package

\*For additional marking information, refer to

Application Note AND8002/D.



#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

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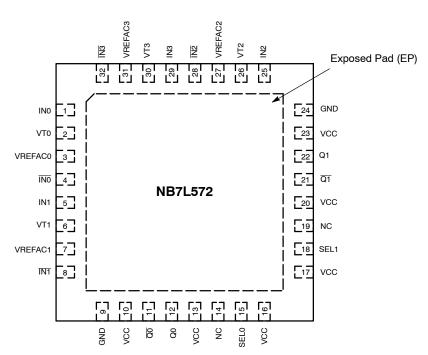


Figure 1. Pinout Configuration (Top View)

**Table 1. INPUT SELECT FUNCTION TABLE** 

	SEL1*	SEL0*	Clock / Data Input Selected			
11/	11/1/1	0	IN0 Input S rec ≥d	M		
VV	<b>V V</b> o <b>V</b> V	1	IN 1 Input S lected	IV		
	1	0	IN2 Input Selected			
	1	1	IN3 Input Selected			

<sup>\*</sup>Defaults HIGH when left open.

**Table 2. PIN DESCRIPTION** 

Pin	Name	I/O	Description	
1, 4 5, 8 25, 28 29, 32	INO, <u>INO</u> IN1, <u>IN1</u> IN2, <u>IN2</u> IN3, <u>IN3</u>	LVPECL, CML, LVDS Input	Non-inverted, Inverted, Differential Clock or Data Inputs.	
2, 6 26, 30	VT0, VT1 VT2, VT3		Internal 100 $\Omega$ Center–tapped Termination Pin for INx / $\overline{\text{INx}}$	
15 18	SEL0 SEL1	LVTTL/LVCMOS Input	Input Select pins, default HIGH when left open through a 28k- $\Omega$ pull-up resistor. Input logic threshold is V <sub>CC</sub> /2. See Select Function, Table 1.	
14, 19	NC	-	No Connect	
10, 13, 16 17, 20, 23	VCC	-	Positive Supply Voltage. All $V_{\rm CC}$ pins must be connected to the positive power s for correct DC and AC operation.	
11, 12 21, 22	Q0, Q0 Q1, Q1	LVPECL Output	Inverted, Non-inverted Differential Outputs.	
9, 24	GND		Negative Supply Voltage, connected to Ground	
3 7 27 31	VREFAC0 VREFAC1 VREFAC2 VREFAC3	-	Output Voltage Reference for Capacitor-Coupled Inputs	
-	EP	-	The Exposed Pad (EP) on the QFN-32 package bottom is thermally connected to the die for improved heat transfer out of package. The exposed pad must be attached to a heat-sinking conduit. The pad is electrically connected to the die, and must be electrically connected to GND.	

In the differential configuration when the input termination pins (VT0, VT1, VT2, VT3) are connected to a common termination voltage or left open, and if no signal is applied on INx / INx input, then the device will be susceptible to self–oscillation.
 All VCC, and GND pins must be externally connected to a power supply for proper operation.

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**Table 3. ATTRIBUTES** 

Characteristi	Value				
ESD Protection	> 4 kV > 150 V				
Input Pullup Resistor (R <sub>PU</sub> )	28 kΩ				
Moisture Sensitivity (Note 3)	Level 1				
Flammability Rating Oxygen Index: 2	UL 94 V-0 @ 0.125 in				
Transistor Count	205				
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test					

<sup>3.</sup> For additional information, see Application Note AND8003/D.

**Table 4. MAXIMUM RATINGS** 

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V <sub>CC</sub>	Positive Power Supply	GND = 0 V		-0.5 to +4.0	V
V <sub>IN</sub>	Positive Input Voltage	GND = 0 V		-0.5 to V <sub>CC</sub> +0.5	V
V <sub>INPP</sub>	Differential Input Voltage $ IN - \overline{IN} $			1.89	V
I <sub>out</sub>	LVPECL Output Current	Continuous Surge		50 100	mA mA
I <sub>IN</sub>	Input Current Through RT (50 Ω Resistor)			± 40	mA
T <sub>A</sub>	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
θ <sub>JA</sub>	Thermal Resistance (Junction-to-Ambient) (Note 4)	0 lfpm 50 0 lfpm	QFN-32 QFN-32	31 27	°C/W °C/W
θЈС	The final Rasistans Junction to— a se) ( Jote 4)		C FN- 2	12	°C/W
T <sub>sol</sub>	Wave Solder	≤ 20 sec		∠65	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

<sup>4.</sup> JEDEC standard multilayer board – 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

Table 5. DC CHARACTERISTICS POSITIVE LVPECL OUTPUT V<sub>CC</sub> = 2.375 V to 3.6 V, GND = 0 V, TA = -40°C to +85°C (Note 6)

Symbol	Characteristic	Min	Тур	Max	Unit	
POWER	SUPPLY				•	•
V <sub>CC</sub>	Power Supply Voltage	/ <sub>CC</sub> = 2.5V <sub>CC</sub> = 3.3 V	2.375 3.0	2.5 3.3	2.625 3.6	V
I <sub>CC</sub>	Power Supply Current for V <sub>CC</sub> (Inputs and Outputs Open)			90	110	mA
LVPECL	OUTPUTS				•	•
V <sub>OH</sub>		<sub>CC</sub> = 2.5 V <sub>CC</sub> = 3.3 V	V <sub>CC</sub> – 1145 1355 2155		V <sub>CC</sub> - 825 1675 2475	mV
V <sub>OL</sub>	Output LOW Voltage (Note 6)  V	V <sub>CC</sub> – 2000 500 1300		V <sub>CC</sub> - 1500 1000 1800	mV	
DIFFERE	NTIAL CLOCK INPUTS DRIVEN SINGLE-ENDED (Figures 4	& 6) (Note 7)			•	
V <sub>IH</sub>	Single-Ended Input HIGH Voltage		V <sub>th</sub> + 100		V <sub>CC</sub>	mV
$V_{IL}$	Single-Ended Input LOW Voltage		GND		V <sub>th</sub> – 100	mV
V <sub>th</sub>	Input Threshold Reference Voltage Range (Note 8)		1100		V <sub>CC</sub> - 100	mV
V <sub>ISE</sub>	Single-Ended Input Voltage (V <sub>IH</sub> - V <sub>IL</sub> )	200		1200	mV	
VREFAC	•					
V <sub>REF-AC</sub>	Output Reference Voltage (100 μA Load)	V <sub>CC</sub> – 1500		V <sub>CC</sub> – 1000	mV	
DIFFERE	NTIAL INPUTS DRIVEN DIFFERENTIALLY (Figures 5 & 7) (N	ote 9)				
$V_{IHD}$	Differential Input HIGH Voltage (IN, IN)		1200		V <sub>CC</sub>	mV
$V_{\text{ILD}}$	Differential Input LOW Voltag		0	1/	V <sub>IIID</sub> -100	mV
$V_{ID}$	Differ in its Ir p it √o tage (IN, No. VI ID - VILD		100	177	1.10	mV
$V_{CMR}$	Ir pu Co nr on 10 le Range Differe vis. Con gurati n, Note (Figure 8)	0)	15	17	V <sub>CC</sub> - 50	mV
I <sub>IH</sub>	Input HIGH Current IN/IN (VT IN/VT IN Open)		-150		150	μΑ
I <sub>IL</sub>	Input LOW Current IN/ĪN (VT IN/VT ĪN Open)	-150		150	μΑ	
CONTRO	L INPUT (SELx Pin)					
$V_{IH}$	Input HIGH Voltage for Control Pin	2.0		V <sub>CC</sub>	V	
$V_{IL}$	Input LOW Voltage for Control Pin	GND		0.8	V	
I <sub>IH</sub>	Input HIGH Current				40	μΑ
I <sub>IL</sub>	Input LOW Current	-215		0	μΑ	
TERMIN/	ATION RESISTORS					
R <sub>TIN</sub>	Internal Input Termination Resistor (Measured from INx to VT	-x)	40	50	60	Ω

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 5. Input and Output parameters vary 1:1 with  $V_{CC}$ .
  6. LVPECL outputs loaded with 50  $\Omega$  to  $V_{CC}$  2V for proper operation.
- 7. Vth, V<sub>IH</sub>, V<sub>IL</sub>, and V<sub>ISE</sub> parameters must be complied with simultaneously.
  8. Vth is applied to the complementary input when operating in single-ended mode.
- 9. V<sub>IHD</sub>, V<sub>ILD</sub>, V<sub>ID</sub> and V<sub>CMR</sub> parameters must be complied with simultaneously.
  10. V<sub>CMR</sub> min varies 1:1 with GND, V<sub>CMR</sub> max varies 1:1 with V<sub>CC</sub>. The V<sub>CMR</sub> range is referenced to the most positive side of the differential input signal.

Table 6. AC CHARACTERISTICS  $V_{CC} = 2.375 \text{ V}$  to 3.6 V, GND = 0 V, TA =  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$  (Note 11)

Symbol	Characteristic			Тур	Max	Unit
f <sub>MAX</sub>	Maximum Input Clock Frequency V <sub>OUT</sub> ≥ 400 mV					GHz
f <sub>DATAMAX</sub>	Maximum Operating Data Rate NRZ, (PRBS23	3)	10.7			Gbps
V <sub>OUTPP</sub>	Output Voltage Amplitude (@ $V_{INPPmin}$ ) (Figure 2 & 9) $f_{in} \le 5$ GHz (Note 12) $f_{in} \le 7$ GHz		550	750		mV
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay to Differential Outputs Measured at Differential Cross-Point	@ 1 GHz INx/INx to Qx/Qx (Figure 9) @ 50 MHz SELx to Qx (Figure 10)	215 100		390 500	ps
t <sub>PD Tempco</sub>	Differential Propagation Delay Temperature Coefficient			115		fs/°C
t <sub>skew</sub>	Output – Output skew (within device) (Note 13) Device – Device skew (tpd max – tpd min)			0	15 100	ps
t <sub>DC</sub>	Output Clock Duty Cycle (Reference Duty Cycle = 50%)			50	55	%
UITTER	Additive Random Clock Jitter, RJ(RMS) (Note 14) $f_{in} = 5.0 \text{ GHz}$ $f_{in} = 7.0 \text{ GHz}$ Data Dependent Jitter, DDJ (Note 15) $6.5 \text{ Gbps}$ $10 \text{ Gbps}$			0.5 0.5	0.8 0.8 15 15	ps rms ps pk-pk
V <sub>INPP</sub>	Input Voltage Swing (Differential Configuration) (Note 16)				1200	mV
t <sub>r,</sub> , t <sub>f</sub>	Output Rise/Fall Times @ 1 GHz; (20% - 80%), V <sub>IN</sub> = 800 mV Q, Q			60	110	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 11. Measured using a 100 mVpk-pk source, 50% duty cycle clock source. All output loading with external 50  $\Omega$  to  $V_{CC}$  2 V. Input edge rates 40 ps (20% - 80%).
- 12. Output voltage swing is a single-ended measurement operating in differential mode.
- 13. Skew is measured between outputs under identical transitions and conditions. Duty cycle skew is defined only for differential operation when the delays are measured from cross-p ross point of the outputs.
- outy cycle clook 14. Additive RMS igna
- 15. Additive P
- lepender junery ith it put NRZ d ta a K28.5. -ended theas unime it operating in diversitial mode 16. Input voltad

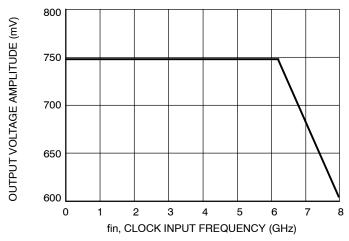


Figure 2. CLOCK Output Voltage Amplitude (V<sub>OUTPP</sub>) / RMS Jitter vs. Input Frequency (f<sub>in</sub>) at **Ambient Temperature (typical)** 

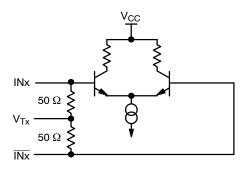


Figure 3. Input Structure

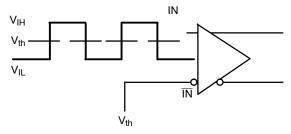


Figure 4. Differential Input Driven Single-Ended

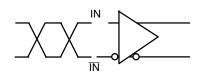


Figure 5. Differential Inputs
Driven Differentially

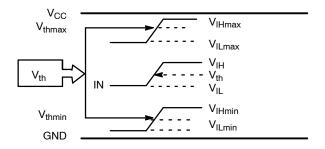


Figure 6. V<sub>th</sub> Diagram

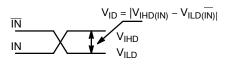


Figure 7. Differential Inputs Driven Differentially

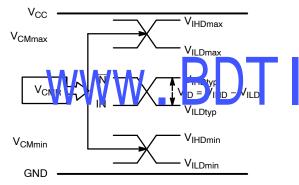


Figure 8. V<sub>CMR</sub> Diagram

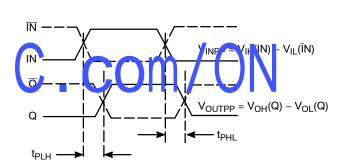


Figure 9. AC Reference Measurement

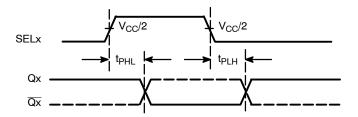


Figure 10. SELx to Qx Timing Diagram

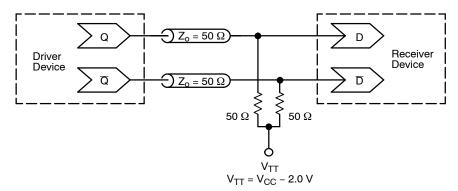


Figure 11. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

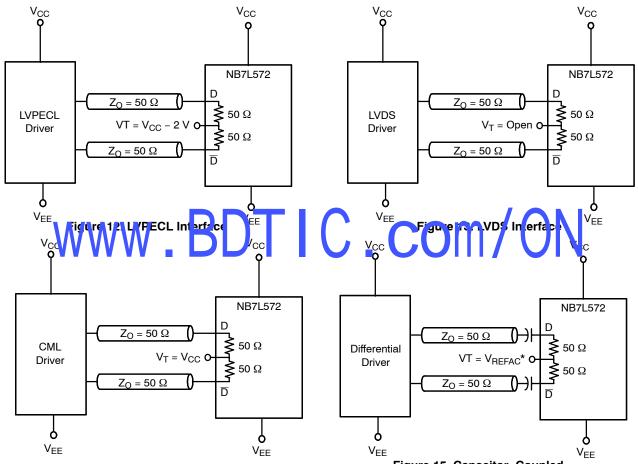


Figure 14. Standard 50  $\Omega$  Load CML Interface

Figure 15. Capacitor–Coupled
Differential Interface
(VT Connected to V<sub>REFAC</sub>)

\* $V_{REFAC}$  bypassed to ground with a 0.01  $\mu F$  capacitor

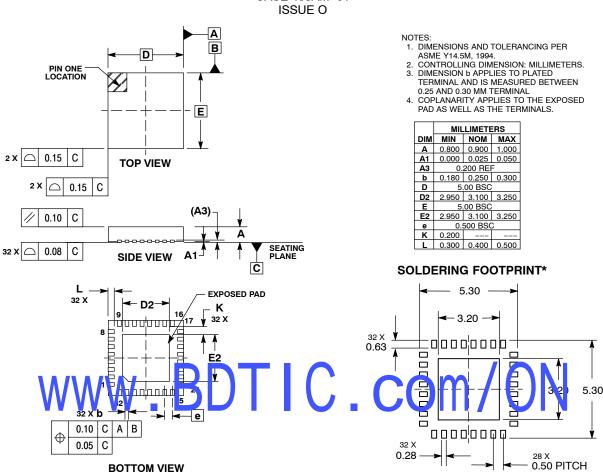
#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NB7L572MNG	QFN32 (Pb-Free)	79 Units / Rail
NB7L572MNR4G	QFN32 (Pb-Free)	1000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

### QFN32 5x5, 0.5P CASE 488AM-01



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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